

Abstract**Wire Saw, Wire Guide Roll and Method for Simultaneously Cutting a Multiplicity of Wafers from an Ingot**

5

The invention relates to a method for simultaneously cutting a multiplicity of wafers from an ingot by means of a structured sawing wire, wherein the structured sawing wire is guided through grooves of two wire guide rolls, and a bottom of each groove, on which the structured wire bears, has a curved groove bottom with a radius of curvature which for each groove is equal to or up to 1.5 times as large as the radius of the envelope of the structured wire, which the structured wire has in the respective groove. The invention furthermore relates to a wire guide roll and to a wire saw.

15 Drawing for the abstract: Fig. 2